

ABSTRACT

5 A substrate processing method capable of suppressing corrosion of a conductive
material on a surface of a substrate by supplying a liquid having a reduced concentration of
dissolved oxygen onto the substrate. The substrate processing method includes: dissolving
an inert gas in a liquid at not less than a saturation solubility to replace oxygen dissolved in
the liquid with the inert gas; generating bubbles of the inert gas in the liquid by
10 depressurizing the liquid in which the inert gas is dissolved; and processing the substrate
while supplying the liquid containing the bubbles to the surface of the substrate.

FIG. 1